SDAS203C - APRIL 1982 - REVISED JANUARY 1995

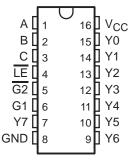
- Combines Decoder and 3-Bit Address Latch
- Incorporates Two Output Enables to Simplify Cascading
- Package Options Include Plastic Small-Outline (D) Packages, Ceramic Chip Carriers (FK), and Standard Plastic (N) and Ceramic (J) 300-mil DIPs

description

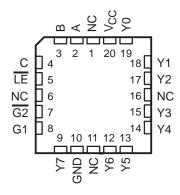
SN54ALS137A, SN74ALS137A, The SN74AS137 are 3-line to 8-line decoders/ demultiplexers with latches on the three address inputs. When the latch-enable (LE) input is low, the devices act as decoders/demultiplexers. When LE goes from low to high, the address present at the select (A. B. and C) inputs is stored in the latches. Further address changes are ignored as long as \overline{LE} remains high. The output-enable controls (G1 and $\overline{G2}$) control the outputs independently of the select or latch-enable inputs. All of the outputs are forced high if G1 is low or $\overline{G2}$ is high. These devices are ideally suited for implementing glitch-free decoders in strobed (stored-address) applications in bus-oriented systems.

The SN54ALS137A is characterized for operation over the full military temperature range of -55°C to 125°C. The SN74ALS137A and SN74AS137 are characterized for operation from 0°C to 70°C.

SN54ALS137A . . . J PACKAGE SN74ALS137A, SN74AS137 . . . D OR N PACKAGE (TOP VIEW)



SN54ALS137A . . . FK PACKAGE (TOP VIEW)



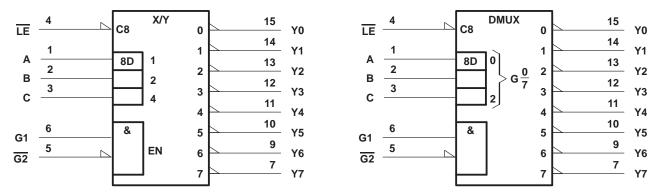
NC - No internal connection

FUNCTION TABLE

		INP	UTS						OUT	PUTS			
	ENABLE	.		SELECT	•				0011	-013			
LE	G1	G2	С	В	Α	Y0	Y1	Y2	Y3	Y4	Y5	Y6	Y7
Х	Х	Н	Χ	Х	Х	Н	Н	Н	Н	Н	Н	Н	Н
Х	L	Χ	Χ	Χ	Χ	Н	Н	Н	Н	Н	Н	Н	Н
L	Н	L	L	L	L	L	Н	Н	Н	Н	Н	Н	Н
L	Н	L	L	L	Н	Н	L	Н	Н	Н	Н	Н	Н
L	Н	L	L	Н	L	Н	Н	L	Н	Н	Н	Н	Н
L	Н	L	L	Н	Н	Н	Н	Н	L	Н	Н	Н	Н
L	Н	L	Н	L	L	Н	Н	Н	Н	L	Н	Н	Н
L	Н	L	Н	L	Н	Н	Н	Н	Н	Н	L	Н	Н
L	Н	L	Н	Н	L	Н	Н	Н	Н	Н	Н	L	Н
L	Н	L	Н	Н	Н	Н	Н	Н	Н	Н	Н	Н	L
Н	Н	L	Χ	Χ	Χ	Out	outs corr	espondir	ng to stor	ed addre	ess = L; a	all others	= H

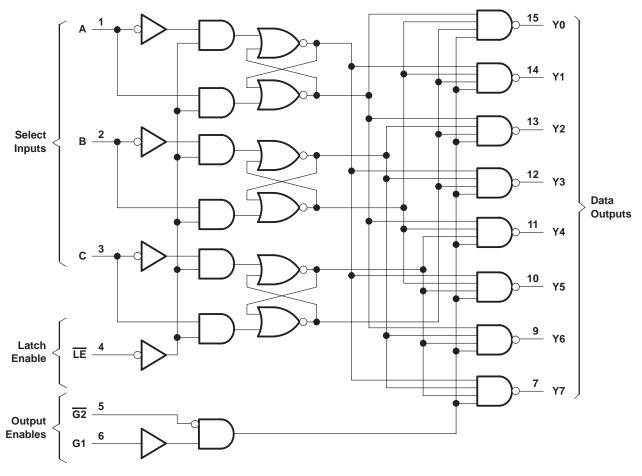
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logic symbols (alternatives)†



[†] These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12. Pin numbers shown are for the D, J, and N packages.

logic diagram (positive logic)



Pin numbers shown are for the D, J, and N packages.



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V _{CC}		 7 V
Input voltage, V _I		 7 V
Operating free-air temperature range, T _A :	SN54ALS137A	 -55°C to 125°C
	SN74ALS137A	 0°C to 70°C
Storage temperature range		-65°C to 150°C

recommended operating conditions

		SN54ALS137A			SN74ALS137A			
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage	4.5	5	5.5	4.5	5	5.5	V
VIH	High-level input voltage	2			2			V
V _{IL}	Low-level input voltage			0.7			8.0	V
IOH	High-level output current			-0.4			-0.4	mA
loL	Low-level output current			4			8	mA
t _W	Pulse duration, LE low	15			10			ns
t _{su}	Setup time at A, B, and C before LE↑	15			10			ns
t _h	Hold time at A, B, and C after LE↑	5			5			ns
TA	Operating free-air temperature	-55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

24244555		TEST CONDITIONS				SN74ALS137A			LINUT
PARAMETER	TEST C					MIN	TYP [‡]	MAX	UNIT
VIK	$V_{CC} = 4.5 V,$	I _I = –18 mA			-1.5			-1.5	V
Voн	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -0.4 \text{ mA}$	V _{CC} -2	2		VCC -2)		V
V	45.7	I _{OL} = 4 mA		0.25	0.4		0.25	0.4	V
V _{OL}	V _{CC} = 4.5 V	$I_{OL} = 8 \text{ mA}$				0.35		0.5	V
lį	$V_{CC} = 5.5 V,$	V _I = 7 V			0.1			0.1	mA
lН	$V_{CC} = 5.5 V$,	V _I = 2.7 V			20			20	μΑ
I _{IL}	$V_{CC} = 5.5 V,$	V _I = 0.4 V			-0.1			-0.1	mA
ΙΟ [§]	$V_{CC} = 5.5 V,$	V _O = 2.25 V	-20		-112	-30		-112	mA
ICC	V _{CC} = 5.5 V			5	11		5	11	mA

 $[\]ddagger$ All typical values are at V_{CC} = 5 V, T_A = 25°C.



[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

[§] The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, IOS.

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switching characteristics (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _C (C _L : R _L : T _A :	UNIT			
			SN54AL MIN	S137A MAX	SN74ALS137A MIN MAX		
t			5	25	5	20	
tPLH telephone	A, B, C	Υ	5	23	3	20	ns
^t PHL	7, 5, 5	•	6	25	6	20	
^t PLH	G 2	Υ	4	15	3	12	ns
t _{PHL}	G2	Y	5	18	4	15	
t _{PLH}	0.4	V	5	21	4	17	
t _{PHL}	G1	Y	5	19	4	15	ns
t _{PLH}	ĪĒ	Υ	7	27	6	22	ns
^t PHL	LE		7	25	7	20	

[†] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage, V _{CC}	7 V
Input voltage, V _I	7 V
Operating free-air temperature range, T _A : SN74AS137	. 0°C to 70°C
Storage temperature range	65°C to 150°C

[‡] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

		SN	LINIT		
		MIN	NOM	MAX	UNIT
Vсс	Supply voltage	4.5	5	5.5	V
V_{IH}	High-level input voltage	2			V
V_{IL}	Low-level input voltage			0.8	V
ІОН	High-level output current			-2	mA
loL	Low-level output current			20	mA
t _W	Pulse duration, LE low	6.5			ns
t _{su}	Setup time at A, B, and C before LE↑	4			ns
th	Hold time at A, B, and C after LE↑	1			ns
TA	Operating free-air temperature	0		70	°C

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	7507 00110	SN	SN74AS137				
PARAMETER	TEST COND	MIN	TYP	MAX	UNIT		
VIK	$V_{CC} = 4.5 V,$	$I_{I} = -18 \text{ mA}$			-1.2	V	
VOH	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V},$	$I_{OH} = -2 \text{ mA}$	V _{CC} -2			V	
V _{OL}	$V_{CC} = 4.5 \text{ V},$	$I_{OL} = 20 \text{ mA}$		0.35	0.5	V	
I _I	$V_{CC} = 5.5 V$,	$V_I = 7 V$			0.1	mA	
I _{IH}	$V_{CC} = 5.5 \text{ V},$	V _I = 2.7 V			20	μΑ	
I _{IL}	$V_{CC} = 5.5 \text{ V},$	V _I = 0.4 V			-1	mA	
10‡	$V_{CC} = 5.5 V,$	V _O = 2.25 V	-30		- 112	mA	
ICC	V _{CC} = 5.5 V			15	24	mA	

 $[\]uparrow$ All typical values are at V_{CC} = 5 V, T_A = 25°C.

switching characteristics (see Figure 1)

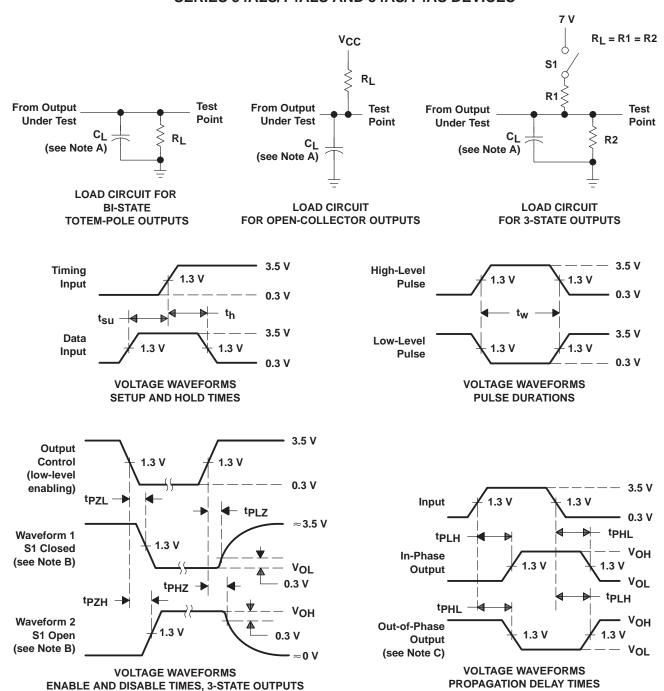
PARAMETER	FROM (INPUT)	$\begin{array}{c} \text{V}_{\text{CC}} = 4.5 \text{ V to } 5.5 \text{ V}, \\ \text{C}_{\text{L}} = 50 \text{ pF}, \\ \text{R}_{\text{L}} = 500 \ \Omega, \\ \text{T}_{\text{A}} = \text{MIN to MAX} \\ \hline \text{SN74AS137} \\ \hline \text{MIN MAX} \end{array}$					
tPLH t	A, B, C	Υ	2	12.5	ns		
[†] PHL	71, 2, 0	'	2	12.5			
^t PLH	G 2	Υ	2	8	, no		
^t PHL	G2	Ť	2	8.5	ns		
^t PLH	64	Υ	2	10	ns		
t _{PHL}	G1	Y	2	9			
tPLH	ĪĒ	Υ	3	13.5	ne		
^t PHL	LE	T	3	14	ns		

[§] For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

[‡] The output conditions have been chosen to produce a current that closely approximates one half of the true short-circuit output current, los.

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PARAMETER MEASUREMENT INFORMATION SERIES 54ALS/74ALS AND 54AS/74AS DEVICES



- NOTES: A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. When measuring propagation delay items of 3-state outputs, switch S1 is open.
 - D. All input pulses have the following characteristics: PRR \leq 1 MHz, $t_f = t_f = 2$ ns, duty cycle = 50%.
 - E. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveforms





PACKAGE OPTION ADDENDUM

17-Mar-2017

PACKAGING INFORMATION

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Orderable Device	Status	Package Type	_	Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
SN74ALS137AD	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	ALS137A	Samples
SN74ALS137AN	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS137AN	Samples
SN74ALS137ANE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	SN74ALS137AN	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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PACKAGE OPTION ADDENDUM

17-Mar-2017

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D (R-PDS0-G16)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.



D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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